

μ PC1297CA

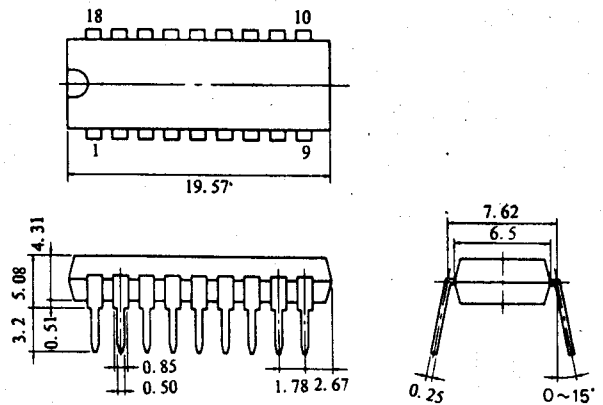
杜比 HX 型降噪处理器

简要说明

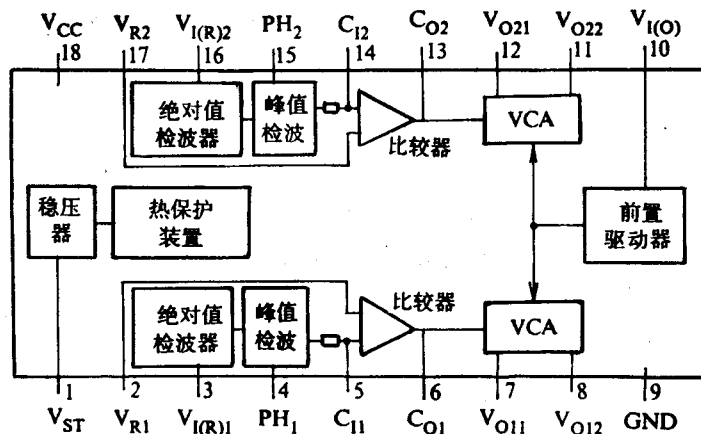
μ PC1297CA 是专为实现杜比 HX PRO 系统而设计的。电路内含绝对值峰值检波电路、比较器、VCA、前置驱动器、稳压电源和热检出保护电路等。

该电路的电源电压范围较宽 ($V_{CC} = 8 \sim 15 \sim 18V$), 二次谐波失真较小 (典型值 $-70dB$)。

外形图



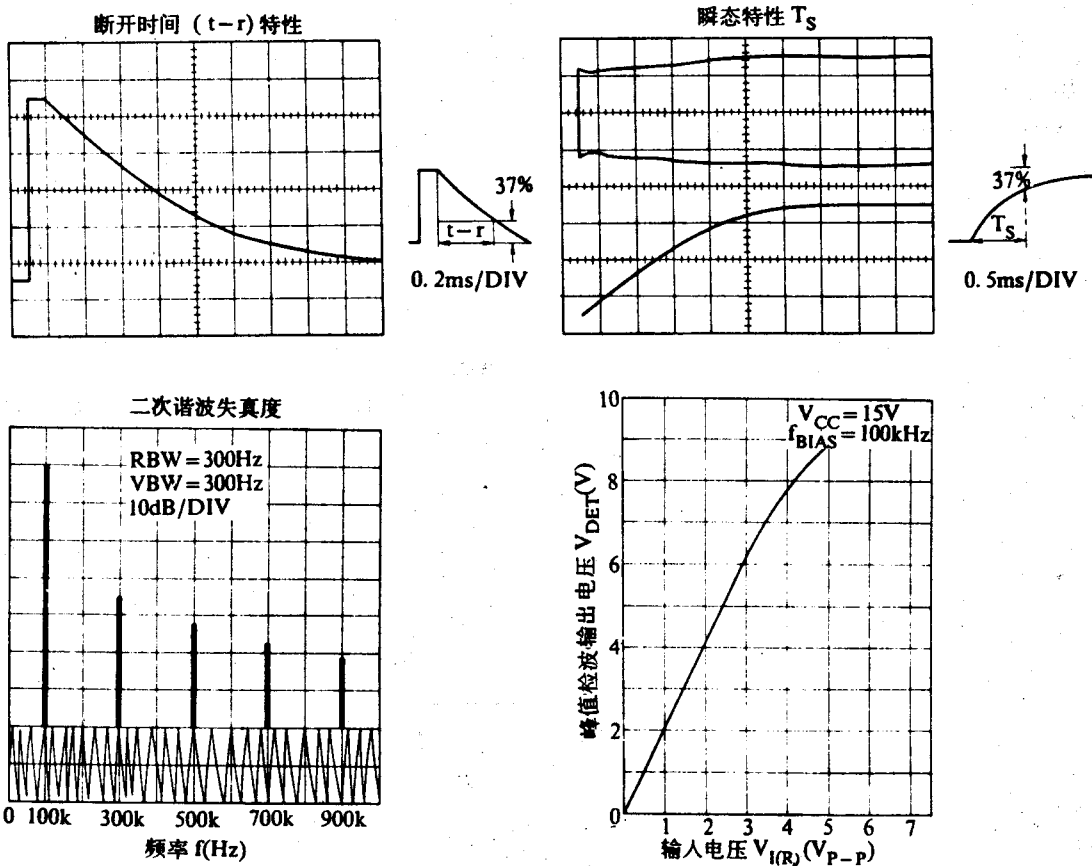
电路框图 [$V_{CC(max)} = 20V, P_{D(max)} = 500mW$]



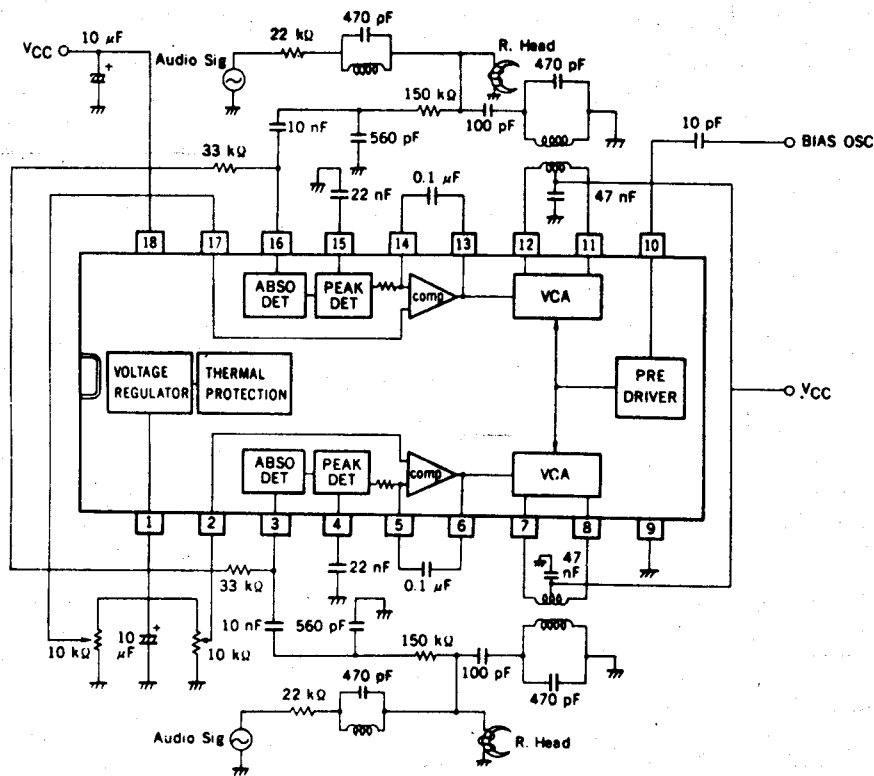
电参数 ($V_{CC} = 15V, f_{BIAS} = 100kHz, V_{I(O)} = 800mV_{p-p}$)

静态电源电流	I_{CC0}	$I_{b1} = I_{b2} = 0$	7mA
偏置电流	I_{BIAS1}	$V_{REF} = 0$	$\leq 10mA$
	I_{BIAS2}	$V_{REF} = V_{st}$	16mA
二次谐波失真度	2nd Harm	$V_{REF} = V_{st}$	$\leq -46dB$
开始时间	t_a	$C_1 = 22nF \pm 1\%$	$\leq 5.0\mu s$
复原时间	t_r	$C_1 = 22nF \pm 1\%$	0.7ms
瞬态特性	T_S	$V_{REF} = \frac{1}{3}, \frac{2}{3} V_{st}$	1.3ms
稳定电压	V_{st}	1 端	4.4V
温度特性	dV_{st}/dT_{op}	1 端, $T_{op} = -25 \sim +75^\circ C$	$-1 \sim +1mV/^\circ C$
输出电流	I_o	自 1 端	$\geq 3mA$
比较器输入偏置电流	I_{b1}		$-0.5 \sim 0\mu A$
输入电阻	R_i	10 端	3.3k Ω

特点与性能



典型应用



BIPOLAR ANALOG INTEGRATED CIRCUIT

μ PC1297

INTEGRATED CIRCUIT FOR DOLBY HX PRO SYSTEM



DESCRIPTION

The μ PC1297 is a monolithic integrated circuit specifically designed to realize the Dolby HX PRO system.

Dolby HX PRO optimizes the recording process by adjusting the level of applied ultrasonic bias in accordance with the self-biasing effect of program material, thus maintaining a constant level of effective bias.

The IC is encapsulated in 18 pin shrink dual-in-line plastic package. Available only to licensees of Dolby Laboratories Licensing Corporation, San Francisco, from whom licensing and application information must be obtained.

"Dolby", the Double-D symbol, and "HX PRO" are trade marks of Dolby Laboratories Licensing Corporation.

FEATURES

- Wide operating voltage. $V_{CC}=8$ to 15 to 18 V
- 2ch. system requires only one chip.
- Low 2nd harmonic distortion. -70 dB TYP.
- Independent of variations in erase voltage.
- Regulated voltage for VCA is provided internally.
- Internal thermal protection circuit.

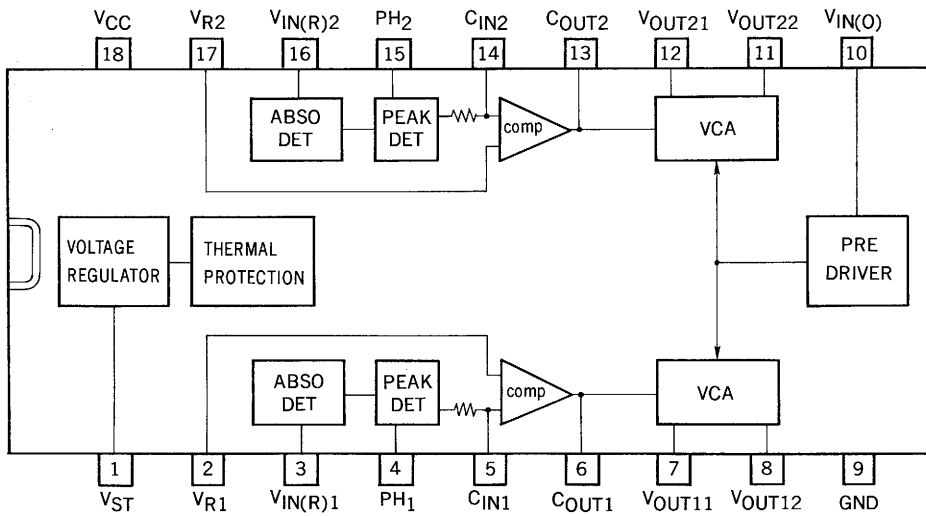
ORDERING INFORMATION

PART NUMBER	PACKAGE	QUALITY GRADE
μ PC1297CA	18 PIN PLASTIC SHRINK DIP (300 mil)	Standard

Please refer to "Quality grade on NEC Semiconductor Devices" (Document number IEI-1209) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

The information in this document is subject to change without notice.

BLOCK DIAGRAM



CONNECTION DIAGRAM

NO.	CONNECTION
1	VOLTAGE REGULATOR
2	COMP REF ₁
3	SIGNAL INPUT ₁
4	PEAK HOLD ₁
5	COMP INPUT ₁
6	COMP OUTPUT ₁
7	VCA OUTPUT ₁₁
8	VCA OUTPUT ₁₂
9	GND
10	BIAS OSC INPUT
11	VCA OUTPUT ₂₁
12	VCA OUTPUT ₂₂
13	COMP OUTPUT ₂
14	COMP INPUT ₂
15	PEAK HOLD ₂
16	SIGNAL INPUT ₂
17	COMP REF ₂
18	V _{CC}

ABSOLUTE MAXIMUM RATINGS (T_a = 25 °C)

Supply Voltage	V _{CC}	20	V
Power Dissipation	P _D	500*	mW
Operating Temperature Range	T _{opt}	-25 to +75	°C
Storage Temperature Range	T _{stg}	-40 to +125	°C

* Value at T_a = 75 °C

RECOMMENDED OPERATING CONDITIONS (T_a = 25 °C)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply Voltage	V _{CC}	8	15	18	V
Bias OSC Input Voltage	V _{in (o)}	0.4	0.8	4.0	V _{p-p}
Signal Input Voltage	V _{in (R)}	0.2	-	4.0	V _{p-p}

ELECTRICAL CHARACTERISTICS ($T_a = 25\text{ }^\circ\text{C}$, $V_{CC} = 15\text{ V}$, $f_{BIAS} = 100\text{ kHz}$, $V_{in(o)} = 800\text{ mV}_{p-p}$)

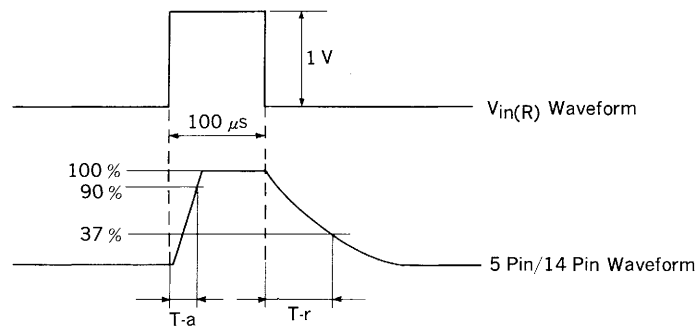
CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION
Supply Current	I_{CC}		7		mA	$I_{b1} = I_{b2} = 0$
Bias Current	I_{BIAS1}			10	μA	$V_{ref} = 0$
	I_{BIAS2}	12	16	20	mA	$V_{ref} = V_{st}$
2nd Harmonic Distortion	2nd Harm		-70	-46	dB	$V_{ref} = V_{st}$
Attack Time	t-a		2.6	5.0	μs	$C_1 = 22\text{ nf} \pm 1\%$ (Note 1)
Release Time	t-r	0.4	0.7	1.1	ms	$C_1 = 22\text{ nf} \pm 1\%$ (Note 1)
Step Response	T_s	0.8	1.3	1.7	ms	$V_{ref} = 1/3, 2/3 V_{st}$ (Note 1)
Stabilized Voltage	V_{st}	4.1	4.4	4.7	V	Pin 1
Temperature Characteristic	dV_{st}/dt_a	-1	0	+1	$\text{mV}/^\circ\text{C}$	Pin 1, $t_a = -25\text{ to }+75\text{ }^\circ\text{C}$
Output Current	I_{out}	3			mA	Form V_{st} Pin
Comparator Input Bias Current	I_{b1}	-0.5	-	0	μA	
Input Resistance	R_{in}	2.3	3.3	4.3	$\text{k}\Omega$	Pin 10

Note 1 t-a, t-r : approx. +0.28 %/°C
 T_s : approx. +0.56 %/°C

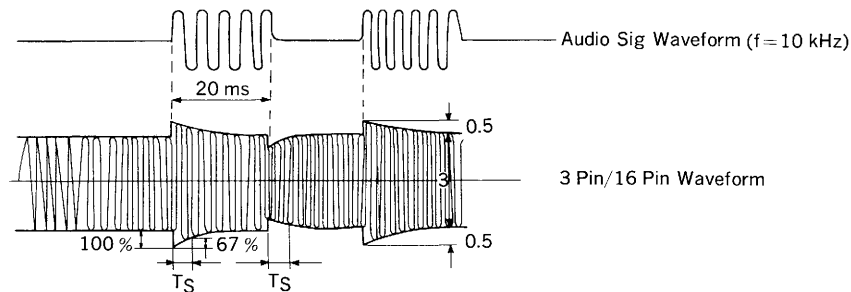
Note 2 Attack and Release Time characteristics are tested by circuit 2, and other characteristics are tested by circuit 1.

TIMING CHART

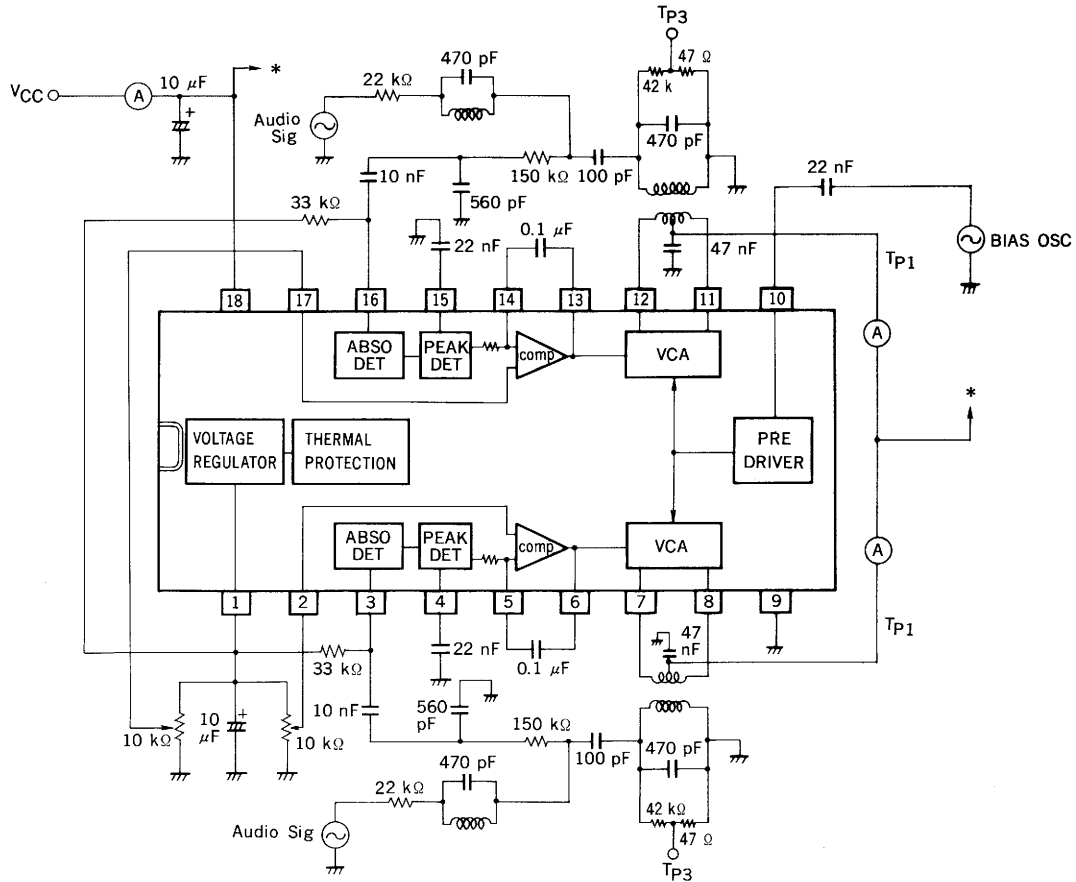
(1) t-a, t-r



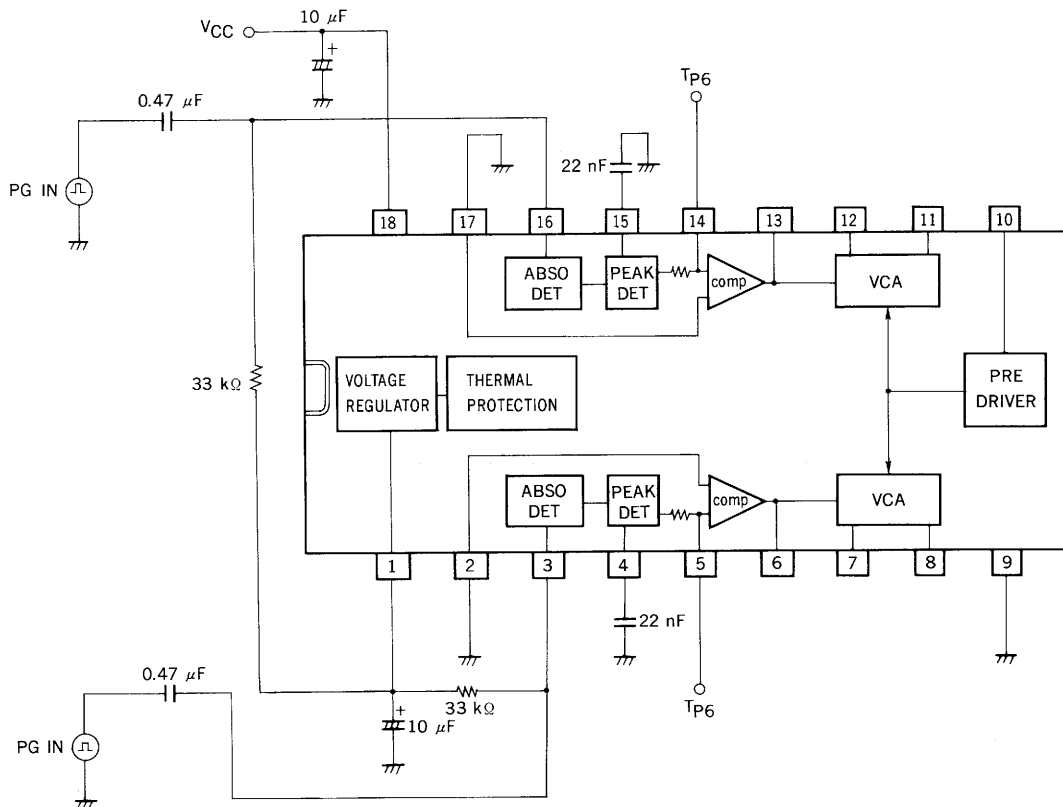
(2) T_s



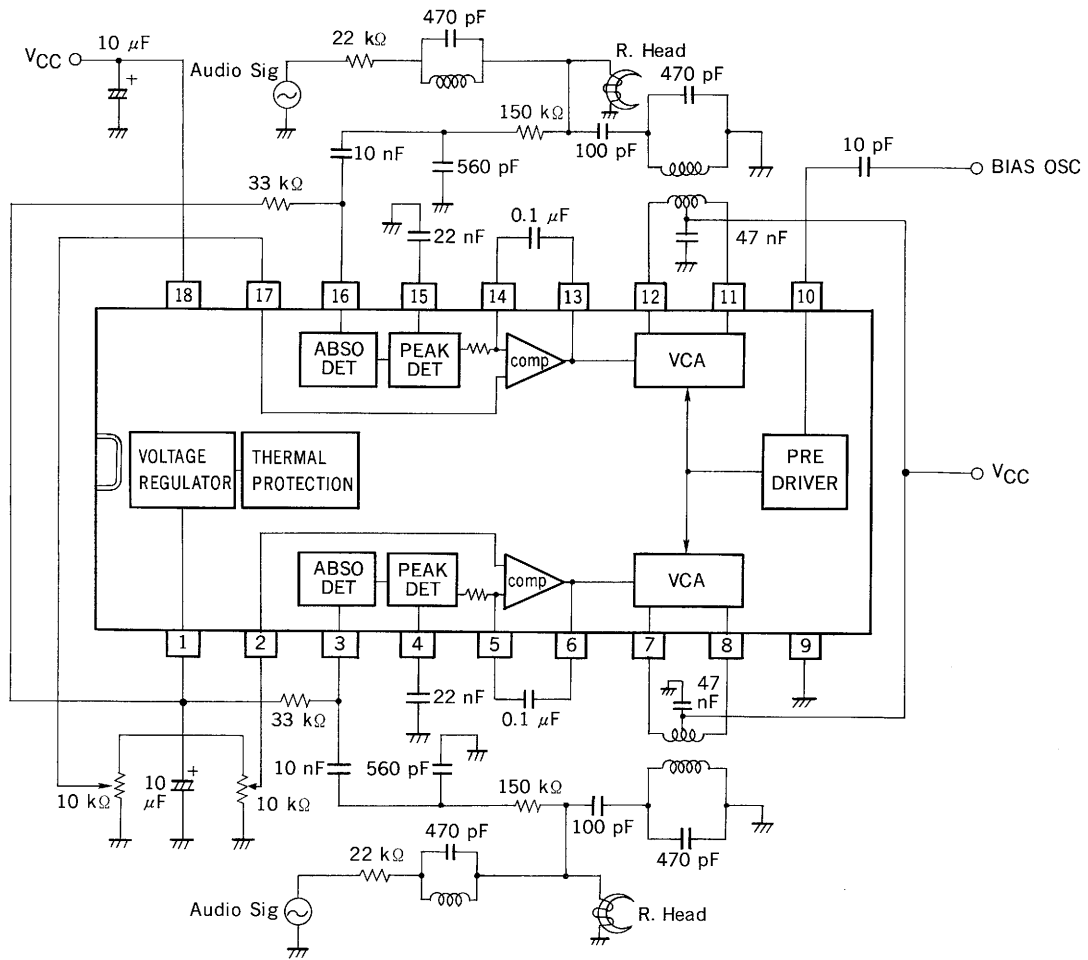
TEST CIRCUIT 1



TEST CIRCUIT 2

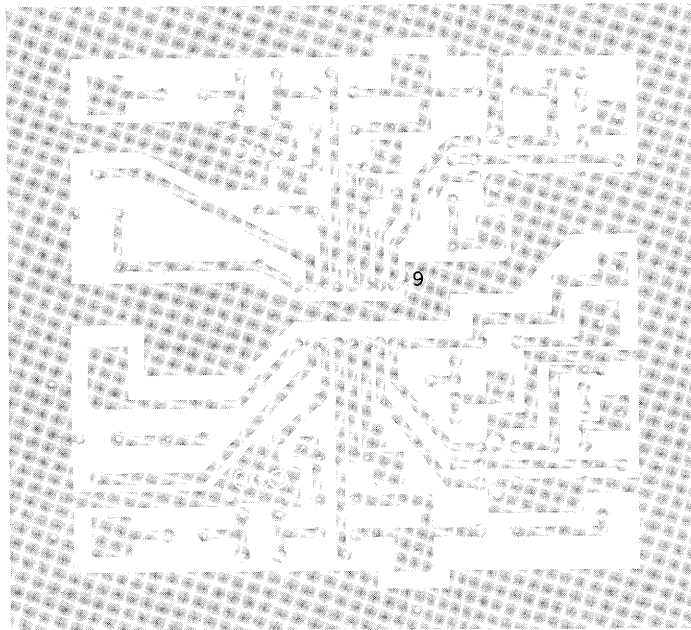


Application Circuit

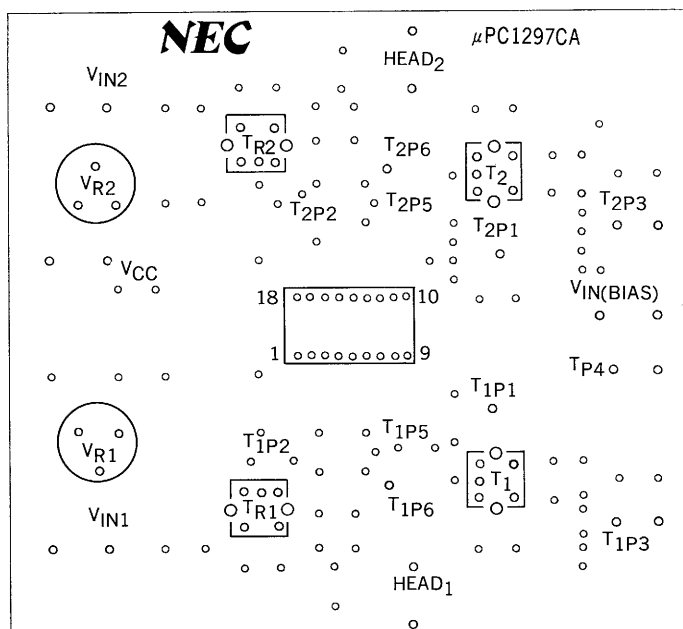


Coil (TOKO, INC)
126ANS-6750ACM

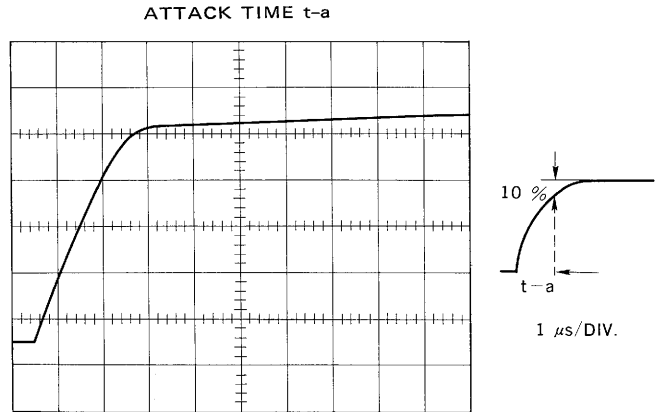
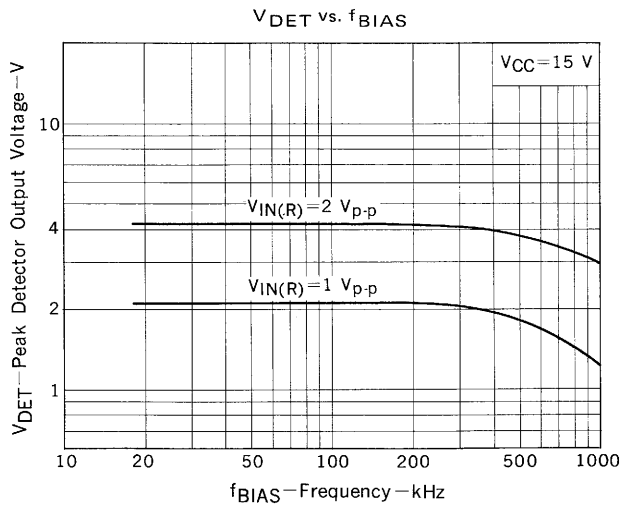
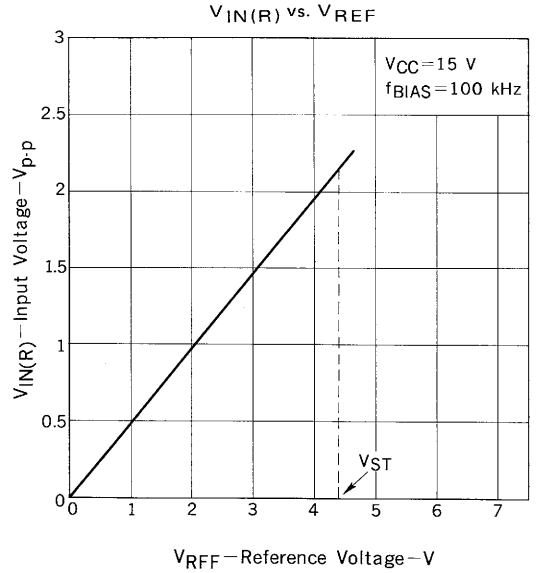
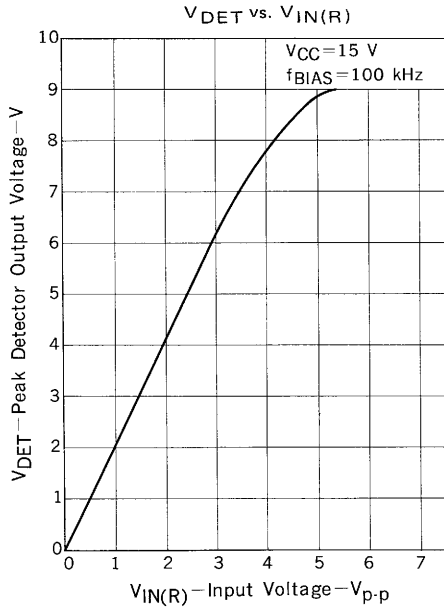
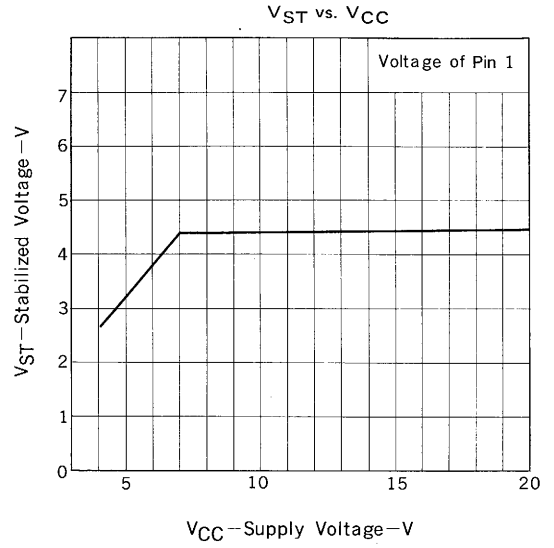
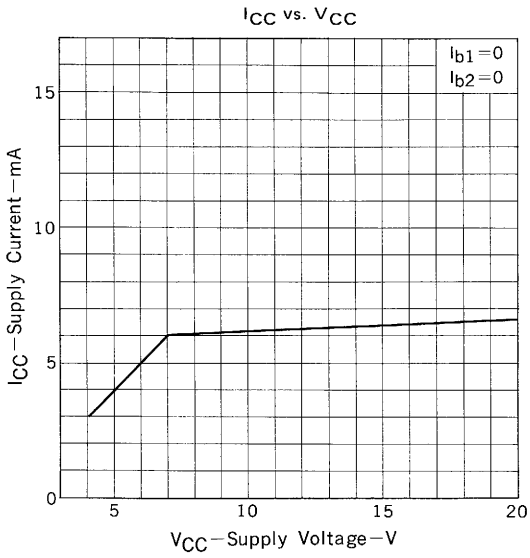
PRINTED CIRCUIT BOARD (Copper foil side)



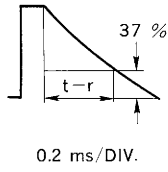
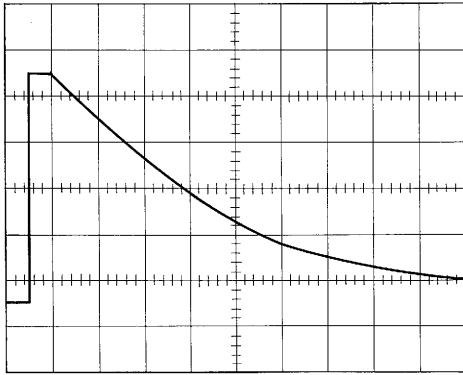
COMPONENT LAYOUT (Component layout side)



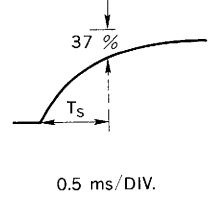
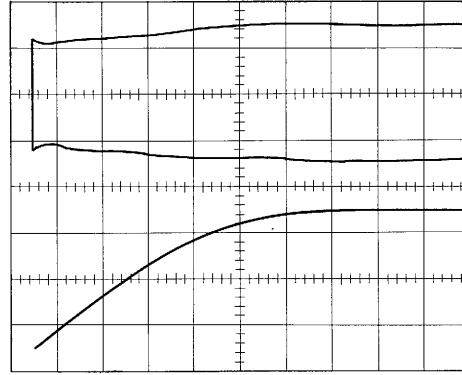
TYPICAL CHARACTERISTICS



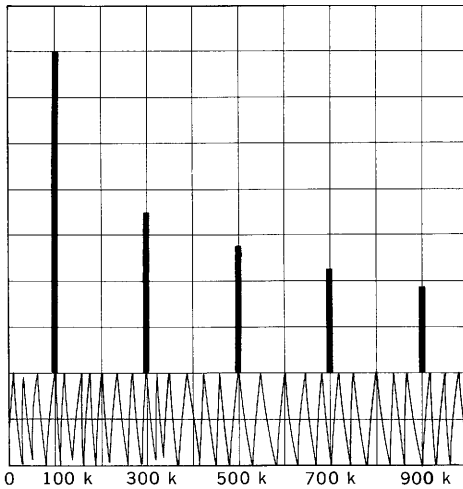
RELEASE TIME t_r



STEP RESPONSE T_s



2ND HARMONIC DISTORTION



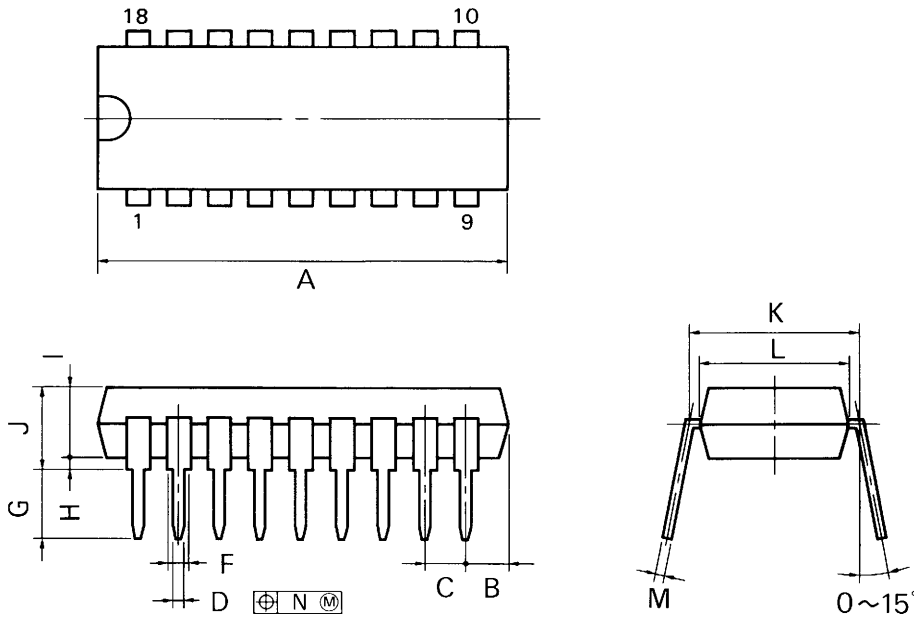
RBW=300 Hz
VBW=300 Hz
10 dB/DIV.

f—Frequency—Hz

Note for use

- μ PC1297 was designed with the help of Bang and Olufsen and Dolby Laboratories Licensing Corporation.
- If you plan to use the μ PC1297 for applications other than Dolby HX PRO, please inform NEC as soon as possible.
- NEC cannot assume any responsibility for any circuits shown or represent that are free from patent infringement.

18PIN PLASTIC SHRINK DIP (300 mil)



P18C-70-300B

NOTES

- 1) Each lead centerline is located within 0.17 mm (0.007 inch) of its true position (T.P.) at maximum material condition.
- 2) Item "K" to center of leads when formed parallel.

ITEM	MILLIMETERS	INCHES
A	19.57 MAX.	0.771 MAX.
B	2.67 MAX.	0.106 MAX.
C	1.778 (T.P.)	0.070 (T.P.)
D	0.50 ^{+0.10}	0.020 ^{+0.004} _{-0.003}
F	0.85 MIN.	0.033 MIN.
G	3.2 ^{+0.3}	0.126 ^{+0.012}
H	0.51 MIN.	0.020 MIN.
I	4.31 MAX.	0.170 MAX.
J	5.08 MAX.	0.200 MAX.
K	7.62 (T.P.)	0.300 (T.P.)
L	6.5	0.256
M	0.25 ^{+0.10} _{-0.05}	0.010 ^{+0.004} _{-0.003}
N	0.17	0.007

★ RECOMMENDED SOLDERING CONDITIONS

The following conditions (see table below) must be met when soldering this product.

For more details, refer to our document "SEMICONDUCTOR DEVICE MOUNTING TECHNOLOGY MANUAL" (IEI-1207).

Please consult with our sales offices in case other soldering process is used, or in case soldering is done under different conditions.

Type of Through Hole Device

μ PC1297CA: 18 pin plastic shrink DIP (300 mil)

Soldering Process	Soldering Conditions
Wave Soldering (For leads only)	Solder temperature: 260 °C or lower. Flow time: 10 seconds or less.
Partial Heating Method	Pin temperature: 260 °C or lower. Time: 10 seconds or less.

Caution: Do not jet molten solder on the surface of package.

[MEMO]

[MEMO]

The application circuits and their parameters are for references only and are not intended for use in actual design-in's.

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Application examples recommended by NEC Corporation

Standard: Computer, Office equipment, Communication equipment, Test and Measurement equipment, Machine tools, Industrial robots, Audio and Visual equipment, Other consumer products, etc.

Special: Automotive and Transportation equipment, Traffic control systems, Antidisaster systems, Anticrime systems, etc.

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